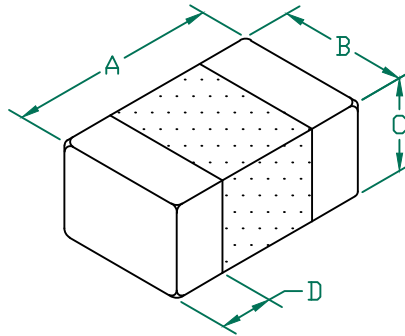


HI0805T500R-10

PHYSICAL DIMENSIONS:

A	2.00 [.079]	+ 0.20 [.008]
B	1.25 [.049]	+ 0.20 [.008]
C	0.90 [.035]	+ 0.20 [.008]
D	0.51 [.020]	+ 0.25 [.010]

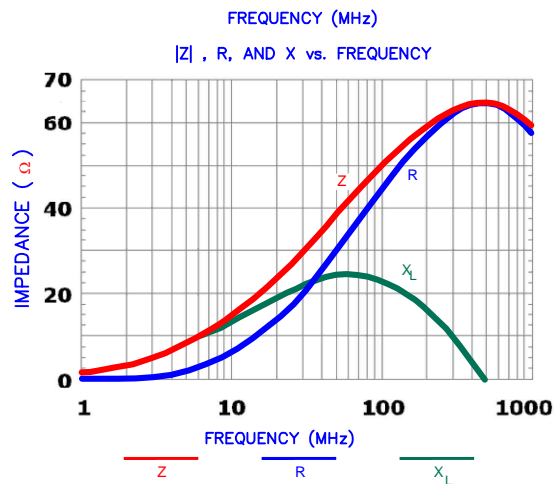
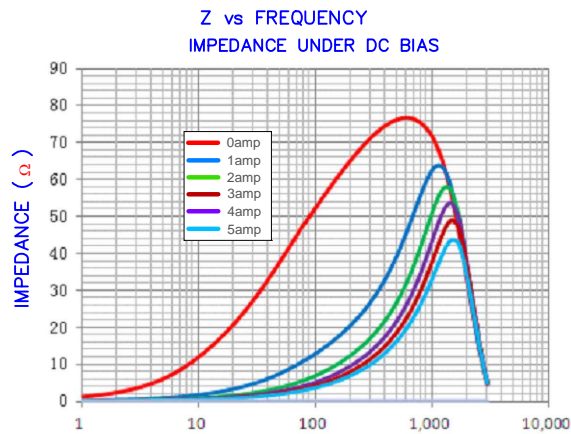


ELECTRICAL CHARACTERISTICS:

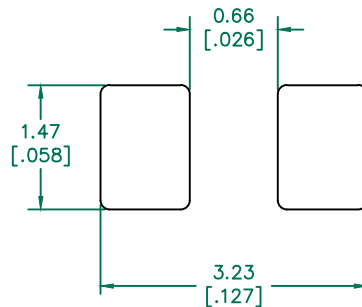
Z @ 100MHz (Ω)	DCR (Ω)	Rated Current
Nominal	50	
Minimum	37	
Maximum	63	0.01
		6000 mA

NOTES: UNLESS OTHERWISE SPECIFIED

1. TAPED AND REELED per CURRENT EIA SPECIFICATIONS 7" REELS, 4000 PCS/REEL, PAPER TAPER.
2. COMPONENTS SHOULD BE ADEQUATELY PREHEATED BEFORE SOLDERING.
3. TERMINATION FINISH IS 100% TIN.
4. OPERATEING TEMPERATURE TEMP: -40°C~+125°C (INCLUDING SELF-HEATING)

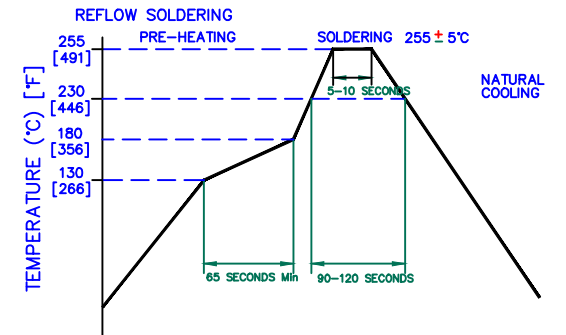


LAND PATTERNS FOR REFLOW SOLDERING



(For wave soldering, add 0.763 [.030] to this dimension.)

RECOMMENDED SOLDERING CONDITIONS



AGILENT E4991A RF Impedance/Material Analyzer
AGILENT 16194A.

DIMENSIONS ARE IN mm [INCHES]				This print is the property of Laird Tech. and is loaned in confidence subject to return upon request and with the understanding that no copies shall be made without the written consent of Laird Tech. All rights to design or invention are reserved.			
C	UPDATE LAIRD LOGO AND NOTES 4	08/05/13	QU	PROJECT/PART NUMBER: HI0805T500R-10		REV: C	PART TYPE: CO-FIRE
B	ADD DC BIAS CURVE	11/01/12	QU	DATE: 11/01/12	SCALE: NTS	DRAWN BY: QU	
A	ORIGINAL DRAFT	03/01/11	QU	CAD #	TOOL #	SHEET: 1 of 1	
REV	DESCRIPTION	DATE	INT	HI0805T500R-10-C			